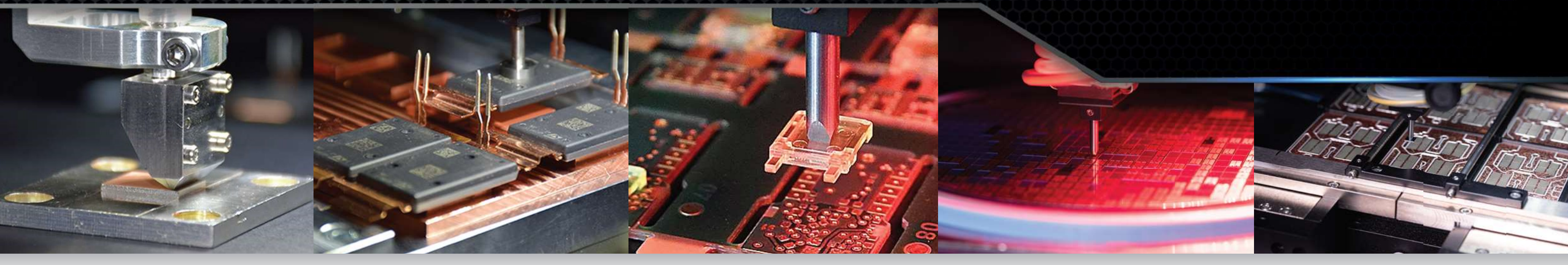
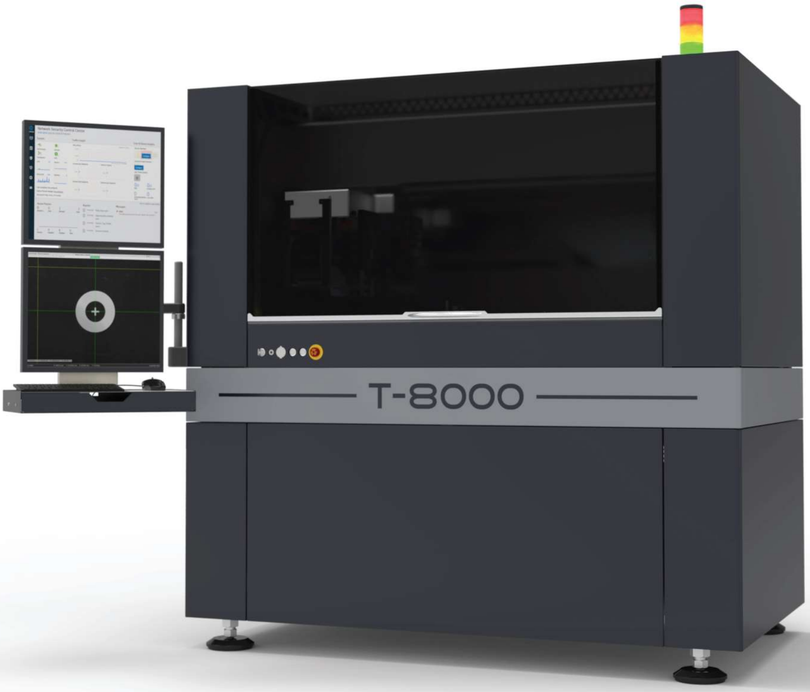
TRESKY
AUTOMATION



T-8000-G

The **T-8000-G** DIE bonder is the result of continuous engineering development and offers a larger working area in which 12-inch wafers can be processed. The bonding system combines precision with versatility and speed based on a generously sized granite gantry that allows for maximum accuracy. Thus, the **T-8000-G** is designed for current and future challenges.



Based on the solid granite chassis, equipped with linear motors and high-resolution direct measuring systems, the machine offers the largest working range within the product portfolio as well as the best bonding performance in the market. In addition, the **T-8000-G** is compatible with numerous existing as well as custom-made options and offers the most versatile process possibilities. The bonder can master any application within the assembly and connection technology and combines precision, versatility and speed. Due to its flexibility and modularity, the **T-8000-G** can be used for prototyping as well as for series production. The manual mode enables fast bonding results without programming.

This model covers all common bonding technologies.

Technical Data

Travel Range with Wafer	590 mm x 560 mm
Wafer Size	2" - 12" (Ring & Frame)
Travel Range w/o Wafer	740 mm x 560mm
Z-Movement	120 mm
Chip Rotation Max.	up to 360°
Bond Force Range	0.01 N - up to 100 N *
Axis Speed	up to 1.8 m/sec
Placement Accuracy	2.5 µm @ 3 sigma
Axis Resolution	XYZ: 0.01 µm, Theta: 0.01°
Min./Max. Comp. Size	0.05 mm - 100 mm

* Higher bond forces on request

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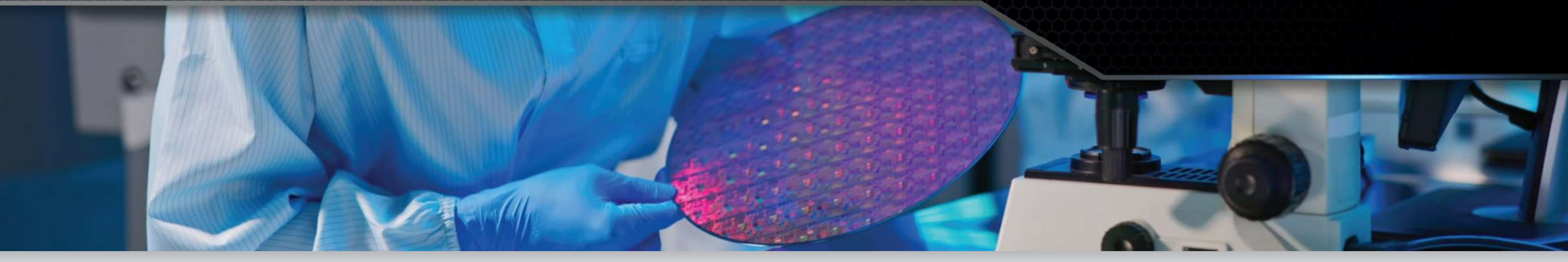

Product Highlights

- Manual mode
- Multichip capable
- Post-bond inspection
- Software programmed temperature control
- Wafermapping
- OCR
- Traceability
- MES
- Automated dispensing needle calibration
- Scrubbing
- Bonding in cavities (15 mm)
- Preform punching

more information

Modules & Options

- Wafer table with DIE ejector
- UV indexer
- WRGB ring light
- Heating plates
- Up to 450 °C
- ΔT ramps up to 60 K/s
- Inert gas
- Automatic tool change
- Various dispensing technologies
- Stamping unit
- Tool heating
- Various feeder widths
- Uplooking camera
- ID Scanner
- DIE flipping unit
- Heated inert gas
- Automatic wafer change
- Magazine feeder
- Inline production
- Formic Acid Module

Bonding Solutions

- Epoxy Bonder
- UV Bonder
- Ultrasonic Bonder
- Thermocompression Bonder
- Sinter Bonder
- Flip Chip Bonder
- Eutectic Bonder
- 3D Bonder
- Photonics Bonder

Applications

- Micro assembly
- Eutectic bonding
- Stamping
- Ultrasonic bonding
- Flip chip bonding
- Thermosonic bonding
- Thermocompression bonding
- Flux dipping
- Epoxy bonding
- DIE stacking

Customized applications

- DTF / DAF bonding
- Multi-DIE bonding
- MEMS
- SMD bonding
- 3D packaging (SiP)
- Laser bar stacking
- Glass bonding
- TO header bonding
- VCSEL bonding
- RFID assembly
- DIE sorting

For more information about our products or services please visit our website.

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